

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A ceramic heater for heating a semiconductor wafer, comprising:

a ceramic substrate ~~in a disc form and~~ having a first surface and a second surface;

a resistance heating element formed on the second surface of said ceramic substrate or inside said ceramic substrate, and including at least two circuits;

~~wherein: said ceramic heater is equipped with:~~

[[a]] temperature-measuring means for measuring the temperature of said ceramic substrate or an object to be heated;

a control unit ~~supplying~~ configured to supply electric power to said heating element;

a memory unit ~~memorizing~~ configured to store the temperature data measured by said temperature-measuring means; and

an operation unit ~~calculating~~ configured to calculate, based on said temperature data, electric power data required for said heating element ~~from said temperature data, said ceramic heater being constituted such that said heating element is divided into at least 2 or more circuits and~~ to attain a uniform temperature of the first surface,

wherein different electric power is supplied to each of the at least two circuits based on the calculated electric power data.

Claim 2 (currently amended): A ceramic heater for heating a semiconductor wafer, comprising:

a ceramic substrate ~~in a disc form and~~ having a first surface and a second surface;

a resistance heating element formed on the second surface of said ceramic substrate or inside said ceramic substrate, and including at least two circuits;

~~wherein: said ceramic heater is equipped with:~~

[[a]] temperature-measuring means for measuring the temperature of said ceramic substrate or an object to be heated;

a power source ~~supplying~~ configured to supply electric power to said heating element;

a control unit ~~controlling~~ configured to control the power source;

a memory unit ~~memorizing~~ configured to store the temperature data measured by said temperature-measuring means; and

~~an operation unit~~ means for calculating, based on said temperature data, electric power data required for said heating element from said temperature data; said ceramic heater being constituted such that said heating element is divided into at least 2 or more circuits and to attain a uniform temperature of the first surface,

wherein different electric power is supplied to each of the at least two circuits based on the calculated electric power data.

Claim 3 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said temperature-measuring means [[is]] comprises a temperature-measuring element.

Claim 4 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said temperature-measuring means [[is]] comprises a thermoviewer.

Claim 5 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said temperature-measuring means [[is]] comprises a temperature-measuring element.

Claim 6 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said temperature-measuring means [[is]] comprises a thermoviewer.

Claim 7 (new): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

Claim 8 (new): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said temperature-measuring means comprises a thermocouple.

Claim 9 (new): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said ceramic heater comprises plural temperature-measuring means.

Claim 10 (new): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

Claim 11 (new): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said temperature-measuring means comprises a thermocouple.

Claim 12 (new): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said ceramic heater comprises plural temperature-measuring means.